

Abstract

A packaged MEMS device containing the micro mirrors has mounted on it at least two distinct integrated circuit chips, at least one of which contains the low-voltage digital-to-analog converters and at least one of which contains the high-voltage amplifiers. The integrated circuit chips may be mounted directly to the MEMS package, or they may be indirectly mounted thereto, e.g., by being directly mounted to a multi-chip module which is in turn mounted on the package. Thus, the MEMS package is employed in a dual role, 1) that of package for the MEMS device and 2) the role of a backplane in that it contains mounting places and the wires interconnecting the MEMS device and chips or modules containing the low-voltage digital-to-analog converters and the high-voltage amplifiers.

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